

## D11 Series

CHD11-R435.72M75K-NB

Pb Free      RoHS Compliant  
2002/95/EC



### ※ Application & Features

- RF, Wireless
- Automotive Equipment at Other
- 8.4×3.6×3.2mm Metal Package
- This specification shall cover the characteristics of 1-port SAW resonator with 435.720M used for remote-control security.

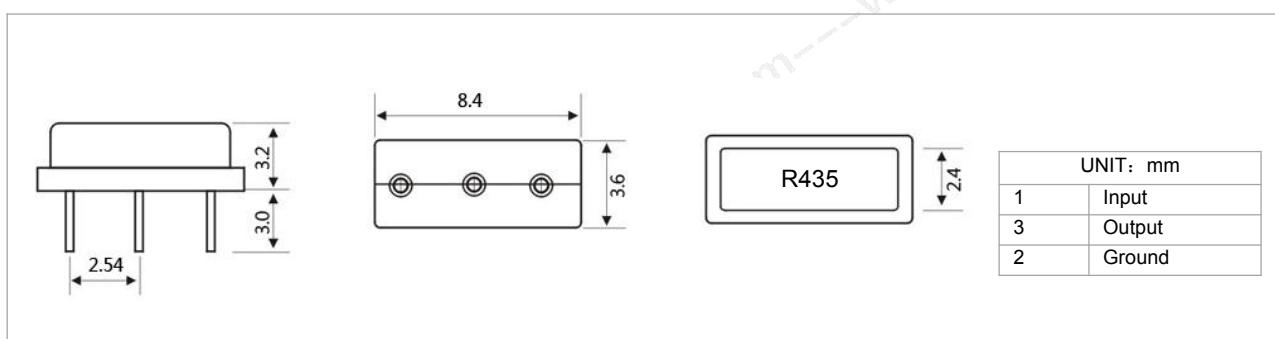
### ※ Maximum Rating

Rating	Value	Unit
CW RF power dissipation	10	dBm
DC voltage between any terminals	$V_{DC}$	V
Operating temperature range	$T_A$	°C
Storage temperature range	$T_{stg}$	°C

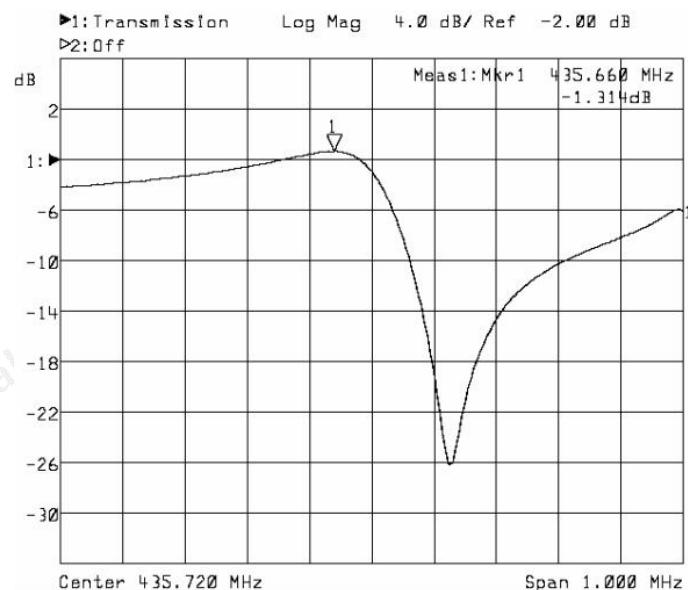
### ※ Electronic Characteristics

Characteristic		Sym	Minimum	Typical	Maximum	Unit
Center Frequency (+25°C)	Absolute Frequency	$f_C$	435.645	435.720	435.795	MHz
	Tolerance from 435.720 MHz	$\Delta f_C$		±75		kHz
Insertion Loss	IL		1.2	2.0		dB
Quality Factor	Unloaded Q	$Q_U$		4.983		
	50 Ω Loaded Q	$Q_L$		650		
Temperature Stability	Turnover Temperature	$T_0$	25	40	55	°C
	Turnover Frequency	$f_0$		$f_0 \pm 2.7$		kHz
	Frequency Temperature Coefficient	FTC		0.032		ppm/°C <sup>2</sup>
Frequency Aging	Absolute Value during the First Year	$ f_A $		≤10		ppm/yr
DC Insulation Resistance Between Any Two Terminals			1.0			MΩ
RF Equivalent RLC Model	Motional Resistance	$R_M$		15	23	Ω
	Motional Inductance	$L_M$		29.926		μH
	Motional Capacitance	$C_M$		4.8865		pF
	Shunt Static Capacitance	$C_0$	1.7	2.0	2.3	pF

### ※ Mechanical Dimensions and Marking

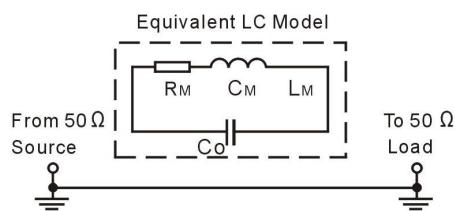


## ※ Typical Frequency Response



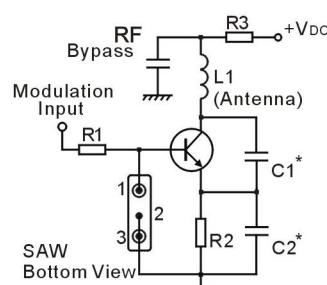
## ※ Equivalent LC Model

## ※ Test Circuit

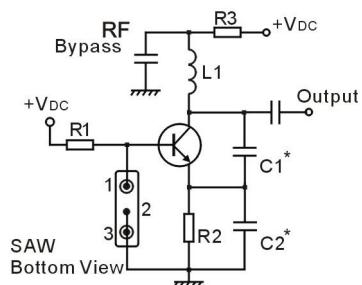


## ※ Typical Application Circuits

### 1) Low-Power Transmitter Application



### 2) Local Oscillator Application



## ※ Environment Characteristic

### 1 Thermal Shock:

The components shall remain within the electrical specifications after being kept at the condition of heat cycle conditions: TA=-40°C±3°C, TB=85°C±2°C, t1=t2=30min, switch time≤3min& cycle time : 100 times, recovery time: 2h±0.5h.

### 2 Resistance to solder heat

Submerge the device terminals into the solder bath at 260°C ±5°C for 10±1 sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in 2.2.

### 3 Solder ability

Submerge the device terminals into the solder bath at 245°C ±5°C for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in 2.2

### 4 The Temperature Storage:

4.1 High Temperature Storage: The components shall remain within the electrical specifications after being kept at the 85°C±2°C for 500h, recovery time : 2h±0.5h.

4.2 Low Temperature Storage: The components shall remain within the electrical specifications after being kept at the -40°C±3°C for 500h, recovery time : 2h±0.5h.

### 5 Humidity test:

The components shall remain within the electrical specifications after being kept at the condition of ambient temperature 60°C±2°C, and 90~96% RH for 500h.

### 6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m for 3 times. The resonator shall fulfill the specifications in 2.2.

### 7 Vibration

Subject the device to the vibration for 2 hour each in X, Y and Z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The resonator shall fulfill the specifications in 2.2.

## ※ Remark

### 1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

### 2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

### 3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.